

Product/ Process Change Notification					
1. PCN No.:		QPCN13003			
2. Subject:		SMB rectifiers dimple shape-/dimension change			
3. To:		All customers who already ordered involved			
		products within the last 3 years			
4. Issued by:		Owen Wang			
5. Issue date:		8-Feb-2013			
6. Proposed first ship date for		8-May-2013			
7. Affected Product Identification					
See attached PCN/PDN involved P/N list.					
8. Change Description : (OLD	Vs. NEW Com	parison)			
Old:		New:			
> See attached comparison report.		➤ See attached comparison report.			
9. Reason for Change:					
Dimple shape/dimension modific	ation for solder	ing process optimization.			
10. Anticipated Impact: (form, fit, function, quality or reliability)					
1. Product outline:	No chang	•			
2. Inner construction changed		onstruction change			
3. Electrical specifications: No change		<u> </u>			
4. Reliability performance: No change					
5. Data sheet: No change					
6. Packing code (order code): No chang					
7. Identification/Traceability:	By date of	code			
11.Qualification plan/result:					
Refer to					
PPAP	Available on demand See attached				
Comparison report 12. Sample availability Date:	See allacried	8-Feb-2013			
13. Tentative implementation date:		8-Feb-2013			
14. Remarks	iale.	0-1 ED-2013			
14. Remarks					
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)		15-Mar-2013			
16. Approved by:		Quayer Chen			



Product/ Process Change Notification Customer Approval Form_QPCN13003

(Please tick the field what is valid for you!)						
	We agree with this proposed change and its schedule.					
	We have object	tions				
	We need more	information:				
	We need more	mormation.				
We need sample:						
Con	npany:					
Nan	ne:					
Add	Iress:					
Sigi	nature:		Date:			